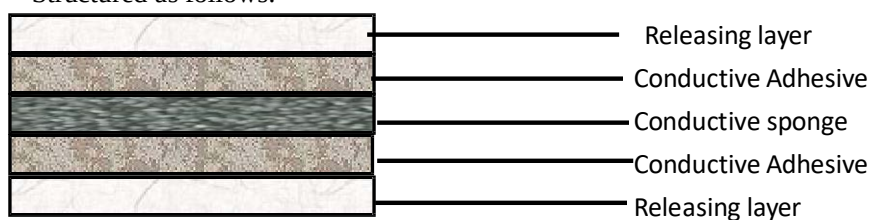


EMI Shielding Conductive Foam Products

Product description

Such products is based on the polyester sponge electroplating, Let conductive particles and metal filaments adsorbed on the surface of PET, to form the structure of full conduction, Then the material on both sides laminated conductive adhesive.

Structured as follows:



The products are very good resilience, can serve as a buffer shielding material, X-Y-Z three have low resistance. Can be flat cutter to die-cutting.

Product Properties

Part Number	Material	Thickness of Material (mm)	Recommendation s of the Working Thickness (mm)	Compression elasticity (%)	Shield Efficacy 10MHz~1GHz(dB)	Conductivity x-y-ohms/inch ²	Holding Power Min/inch	Adhesion Strengthkg/25MM	Conductivity z-ohms/inch ²
G-CF85200D	Conductive sponge	2.0±0.2	0.8~1.8	>35	>60	<0.08	≥1440	≥1.5	<0.05

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Compression performances

Part Number	Actual thickness (mm)	Pressure to 0.4mm required force	Pressure to 0.5mm required force	Pressure to 0.7mm required force	Pressure to 1.0mm required force	Pressure to 1.5mm required force	Pressure to 2.0mm required force
G-CF85200D	2.1	142.6N	82.5N	22.9N	3.1N	0.88N	0.41N
Note: The compressive data in the compression test is the representative data, not the guaranteed one.							

Application

Our EMI Shielding conductive sponge Products with a very low resistance, good shielding effectiveness, to provide special size and specifications of the customer; can apply to the FCC, CE certification standard monitor, desktop computers, notebook computers, mobile phones, cable assemblies and communication devices.

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